

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 70%;">Name</th> <th style="width: 30%;">Execution Date</th> </tr> </thead> <tbody> <tr> <td>Guo-Tsai Huang</td> <td>11/24/2009</td> </tr> <tr> <td>Fu-Jye Liang</td> <td>11/30/2009</td> </tr> <tr> <td>Li-Jui Chen</td> <td>11/30/2009</td> </tr> <tr> <td>Chih-Ming Ke</td> <td>11/30/2009</td> </tr> </tbody> </table>		Name	Execution Date	Guo-Tsai Huang	11/24/2009	Fu-Jye Liang	11/30/2009	Li-Jui Chen	11/30/2009	Chih-Ming Ke	11/30/2009
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CORRESPONDENCE DATA											
<p>Fax Number: (214)200-0853</p> <p><i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 214-651-5000</p> <p>Email: ipdocketing@haynesboone.com</p> <p>Correspondent Name: HAYNES AND BOONE, LLP</p> <p>Address Line 1: 2323 Victory Avenue</p> <p>Address Line 2: Suite 700</p> <p>Address Line 4: Dallas, TEXAS 75219</p>											
ATTORNEY DOCKET NUMBER:	24061.1371										
NAME OF SUBMITTER:	Liem T. Do										
Total Attachments: 3											

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ASSIGNMENT

WHEREAS, we,

- | | | | |
|-----|----------------|----|---|
| (1) | Guo-Tsai Huang | of | ✓ 3F., No. 388, Bihua St., Sanchong city,
Taipei County 241, Taiwan, R.O.C. |
| (2) | Fu-Jye Liang | of | No. 16, Houcuo Road, Xiaogang District
Kaohsiung City 812, Taiwan, R.O.C. |
| (3) | Li-Jui Chen | of | 18F-1, No. 6, Lane 175, Wu-Ling Road
Hsinchu City, Taiwan, R.O.C. |
| (4) | Chih-Ming Ke | of | 9F, No. 17, Alley 7, Lane 298, Sec. 2, Guangfu Road
Hsinchu City 300, Taiwan, R.O.C. |

have invented certain improvements in

METHOD AND APPARATUS OF PROVIDING OVERLAY

for which we have executed an application for Letters Patent of the United States of America,

_____ of even date filed herewith; and
 _____ filed on December 4, 2009 and assigned application no. 12/631,591 and;

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Guo-Tsai Huang

Residence Address: 3F., No. 388, Bihua St. Sanchong city,
Taipei County 241, Taiwan, R.O.C.

Dated: ✓ 2009/11/24

✓ 黃國財 Guo-Tsai Huang
Inventor Signature

Inventor Name: Fu-Jye Liang

Residence Address: No. 16, Houcuo Road, Xiaogang District
Kaohsiung City 812, Taiwan, R.O.C.

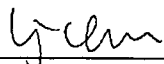
Dated: ✓ 2009/11/30

✓ Fu-Jye Liang
Inventor Signature

Inventor Name: Li-Jui Chen


Residence Address: 18F-1, No. 6, Lane 175, Wu-Ling Road
Hsinchu City, Taiwan, R.O.C.

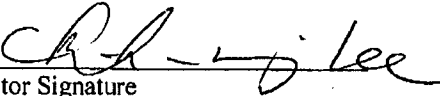
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✓ 
Inventor Signature

Inventor Name: Chih-Ming Ke

Residence Address: 9F, No. 17, Alley 7, Lane 298, Sec. 2, Guangfu Road
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2009/11/30
Dated: ✓ 

✓ 
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